

ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
INPUT				
Reverse voltage		V_R	6	V
Forward current - continuous		I_F	60	mA
Power dissipation		P_{diss}	100	mW
OUTPUT				
Off state output terminal voltage		V_{DRM}	600	V
Peak non-repetitive surge current	PW = 100 ms, 120 pps	I_{TSM}	1	A
Power dissipation		P_{diss}	200	mW
On-state RMS current		$I_{T(RMS)}$	100	mA
COUPLER				
Total power dissipation		P_{tot}	300	mW
Operating temperature		T_{amb}	-55 to +100	$^{\circ}\text{C}$
Storage temperature		T_{stg}	-55 to +150	$^{\circ}\text{C}$
Soldering temperature	10 s	T_{slid}	260	$^{\circ}\text{C}$

Note

- Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability

THERMAL CHARACTERISTICS				
PARAMETER	SYMBOL	VALUE	UNIT	
Maximum LED junction temperature	$T_{jmax.}$	125	$^{\circ}\text{C}$	
Maximum output die junction temperature	$T_{jmax.}$	125	$^{\circ}\text{C}$	
Thermal resistance, junction emitter to board	θ_{JEB}	150	$^{\circ}\text{C}/\text{W}$	
Thermal resistance, junction emitter to case	θ_{JEC}	139	$^{\circ}\text{C}/\text{W}$	
Thermal resistance, junction detector to board	θ_{JDB}	78	$^{\circ}\text{C}/\text{W}$	
Thermal resistance, junction detector to case	θ_{JDC}	103	$^{\circ}\text{C}/\text{W}$	
Thermal resistance, junction emitter to junction detector	θ_{JED}	496	$^{\circ}\text{C}/\text{W}$	
Thermal resistance, case to ambient	θ_{CA}	3563	$^{\circ}\text{C}/\text{W}$	

Note

- The thermal model is represented in the thermal network below. Each resistance value given in this model can be used to calculate the temperatures at each node for a given operating condition. The thermal resistance from board to ambient will be dependent on the type of PCB, layout and thickness of copper traces. For a detailed explanation of the thermal model, please reference Vishay's Thermal Characteristics of Optocouplers application note



ELECTRICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)							
PARAMETER	TEST CONDITION	PART	SYMBOL	MIN.	TYP.	MAX.	UNIT
INPUT							
Reverse current	$V_R = 6\text{ V}$		I_R	-	-	10	μA
Forward voltage	$I_F = 30\text{ mA}$		V_F	-	1.2	1.5	V
OUTPUT							
Leakage with LED off, either direction	$V_{DRM} = 600\text{ V}$		I_{DRM}	-	10	500	nA
Critical rate of rise off-state voltage	$V_D = 400\text{ V}$		dV/dt_{cr}	1500	2000	-	V/ μs
COUPLER							
LED trigger current, current required to latch output		VO3053	I_{FT}	-	-	5	mA
		VO3052	I_{FT}	-	-	10	mA
Peak on-state voltage, either direction	$I_{TM} = 100\text{ mA peak}$, $I_F = \text{rated } I_{FT}$		V_{TM}	-	1.7	3	V
Holding current, either direction			I_H	-	200	-	μA
Coupling capacitance	10 kHz		C_{IO}	-	0.4	-	pF

Note

- Typical values are characteristics of the device and are the result of engineering evaluations. Typical values are for information only and are not part of the testing requirements.

SAFETY AND INSULATION RATINGS				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Climatic classification	According to IEC 68 part 1		55 / 100 / 21	
Pollution degree	According to DIN VDE 0109		2	
Comparative tracking index	Insulation group IIIa	CTI	175	
Maximum rated withstanding isolation voltage	According to UL1577, $t = 1\text{ min}$	V_{ISO}	4420	V_{RMS}
Tested withstanding isolation voltage	According to UL1577, $t = 1\text{ s}$	V_{ISO}	5300	V_{RMS}
Maximum transient isolation voltage	According to DIN EN 60747-5-5	V_{IOTM}	8000	V_{peak}
Maximum repetitive peak isolation voltage	According to DIN EN 60747-5-5	V_{IORM}	890	V_{peak}
Isolation resistance	$T_{amb} = 25\text{ }^{\circ}\text{C}$, $V_{IO} = 500\text{ V}$	R_{IO}	$\geq 10^{12}$	Ω
	$T_{amb} = 100\text{ }^{\circ}\text{C}$, $V_{IO} = 500\text{ V}$	R_{IO}	$\geq 10^{11}$	Ω
Output safety power		P_{SO}	500	mW
Input safety current		I_{SI}	250	mA
Input safety temperature		T_S	175	$^{\circ}\text{C}$
Creepage distance	DIP-6, SMD-6 with option 7 and 9		≥ 7	mm
Clearance distance			≥ 7	mm
Creepage distance	DIP-6, 400 mil, option 6		≥ 8	mm
Clearance distance			≥ 8	mm
Insulation thickness		DTI	≥ 0.4	mm
Input to output test voltage, method A	$V_{IORM} \times 1.6 = V_{PR}$, 100 % sample test with $t_M = 10\text{ s}$, partial discharge $< 5\text{ pC}$	V_{PR}	1669	V_{peak}

Note

- As per IEC 60747-5-5, § 7.4.3.8.2, this optocoupler is suitable for “safe electrical insulation” only within the safety ratings. Compliance with the safety ratings shall be ensured by means of protective circuits



TYPICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

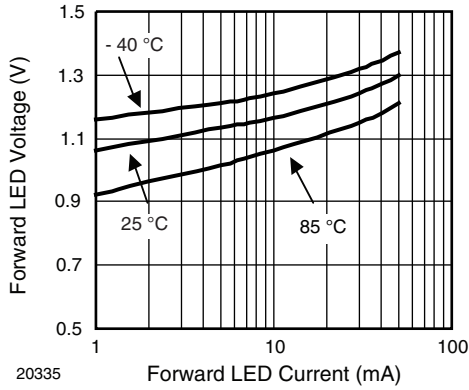


Fig. 1 - Forward Voltage vs. Forward Current

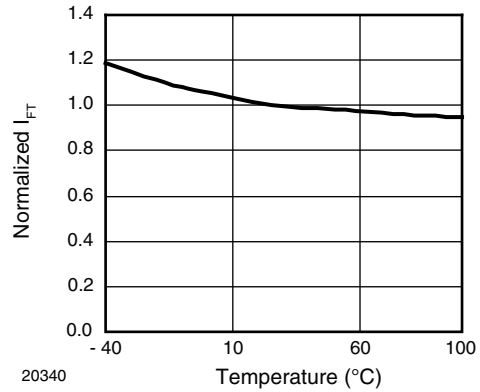


Fig. 4 - Normalized Trigger Current vs. Temperature

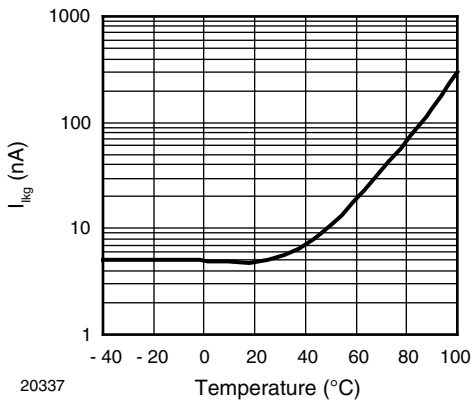


Fig. 2 - Off-State Leakage Current vs. Temperature

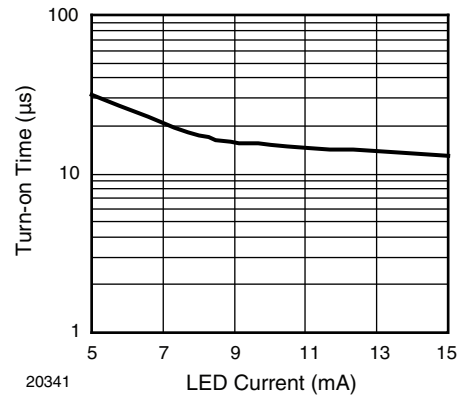


Fig. 5 - Turn-on Time vs. LED Current

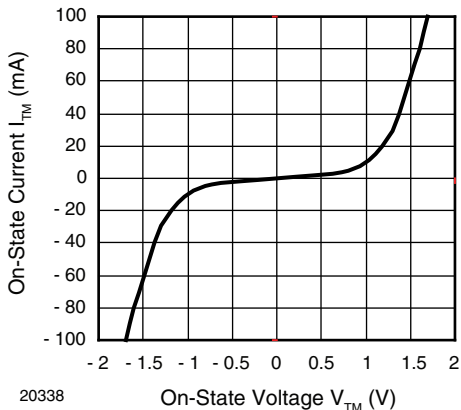


Fig. 3 - On-State Current vs. V_{TM}

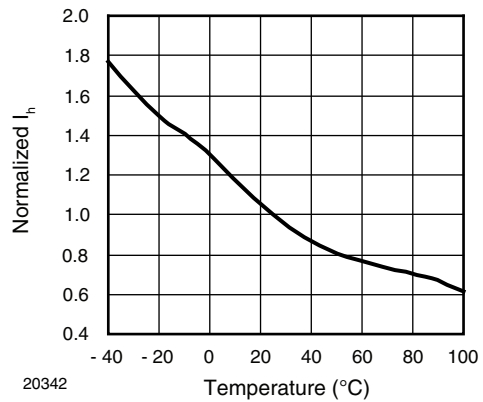


Fig. 6 - Normalized Holding Current vs. Temperature

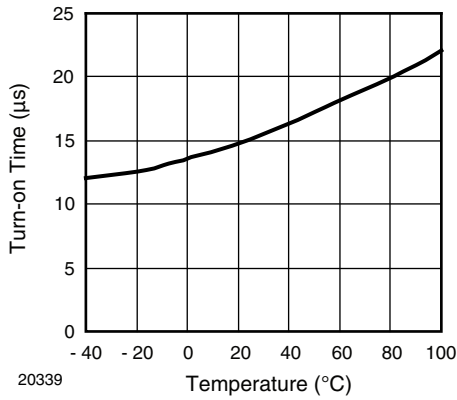


Fig. 7 - Turn-on Time vs. Temperature

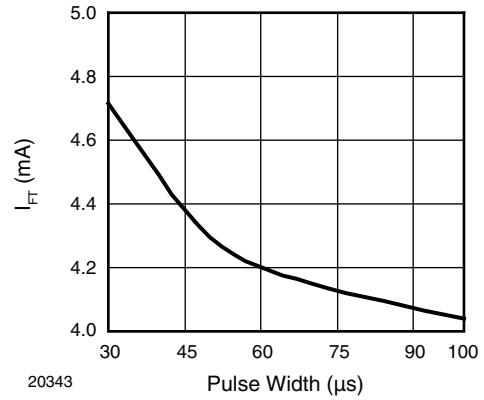
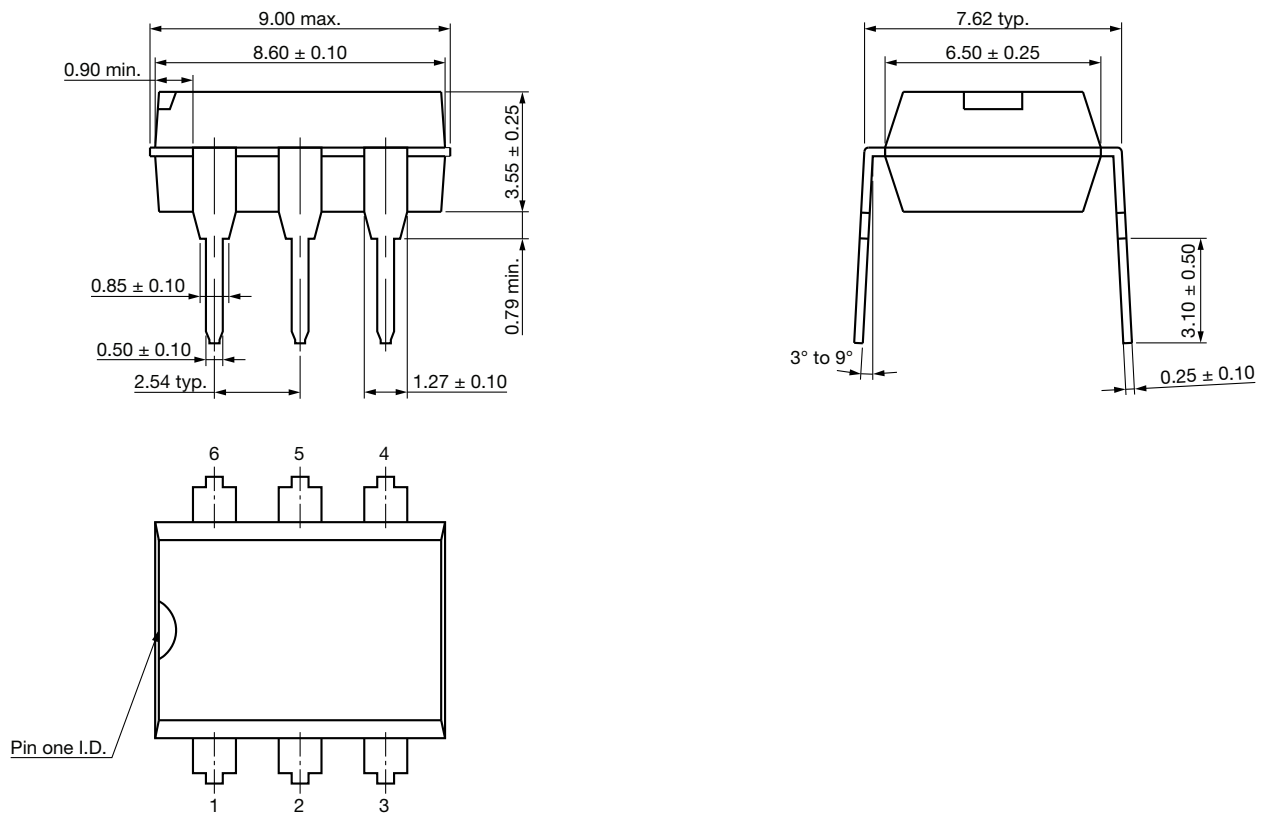


Fig. 8 - Trigger Current vs. Pulse Width

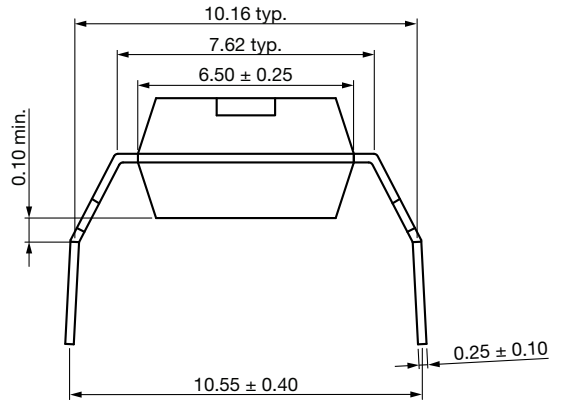
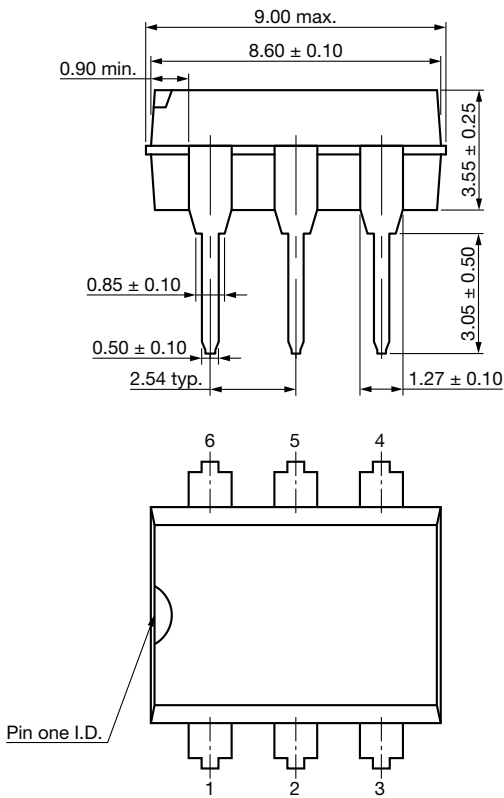
PACKAGE DIMENSIONS (in millimeters)

DIP-6

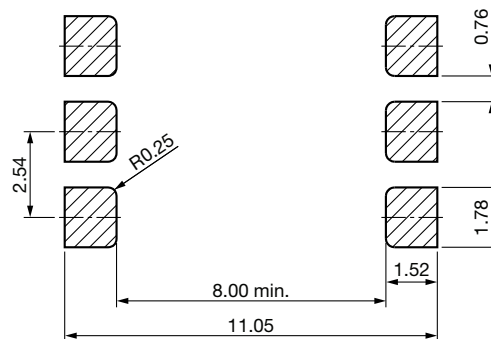
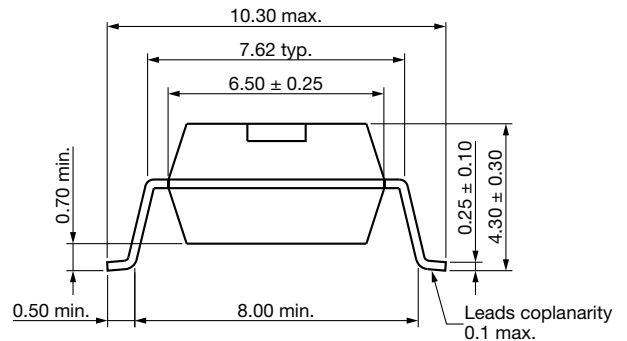
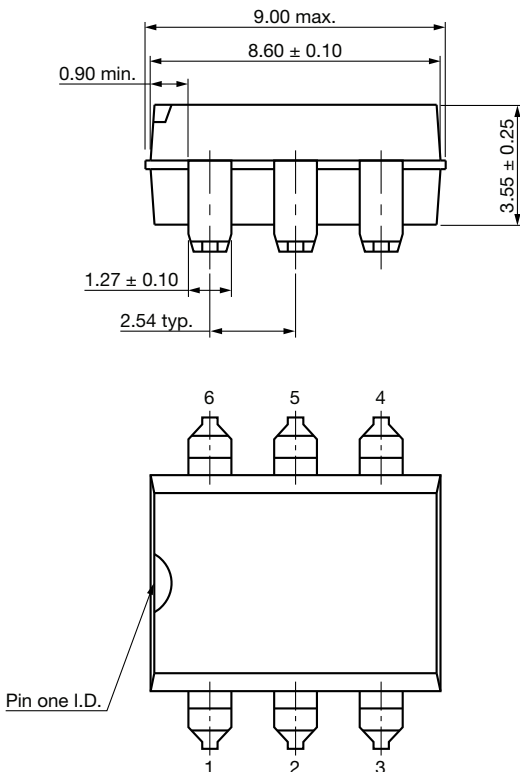




DIP-6, 400 mil, Option 6

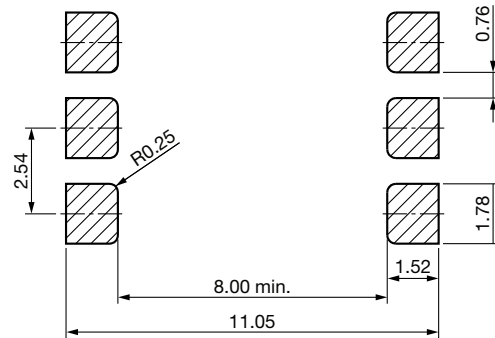
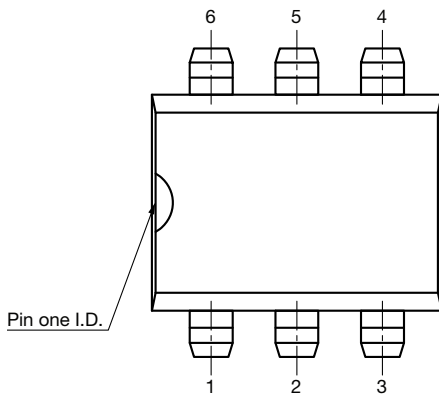
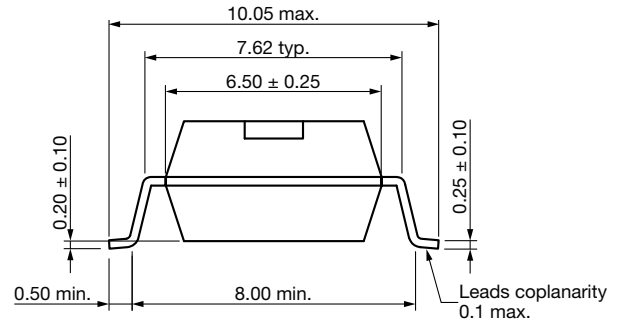
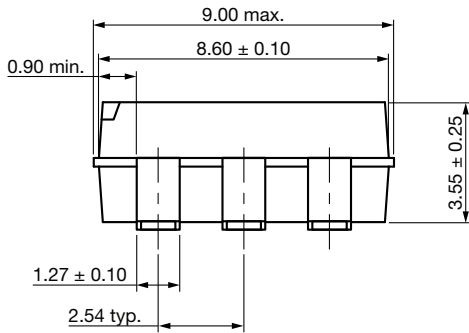


SMD-6, Option 7

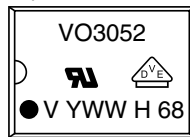




SMD-6, Option 9



PACKAGE MARKING (example of VO3052-X016)



Notes

- The VDE logo is only marked on option1 parts
- Tape and reel suffix (T) is not part of the package marking

PACKING INFORMATION (in millimeters)

Tube

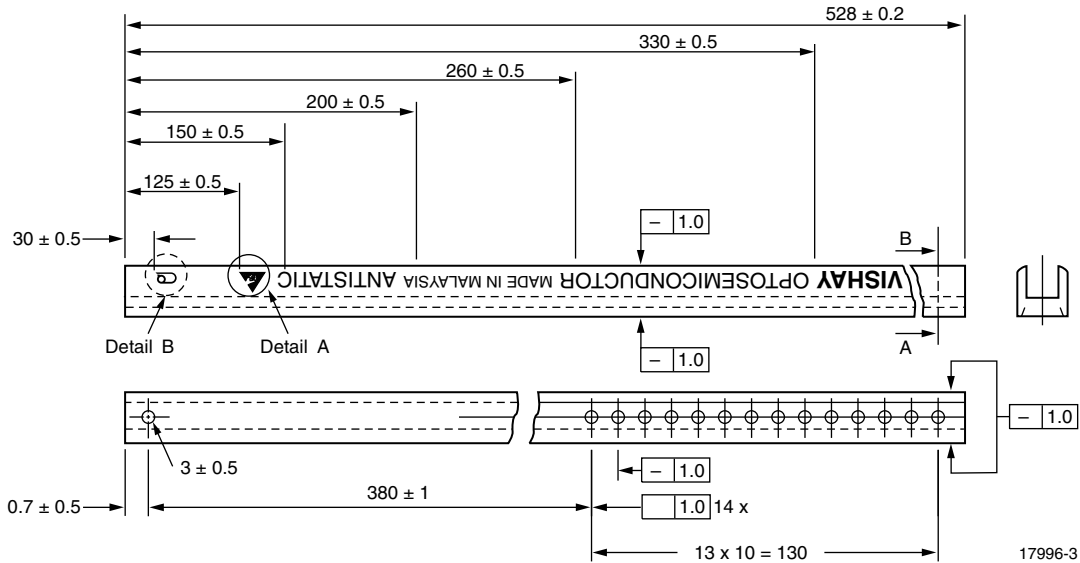


Fig. 9 - Shipping Tube Specifications for DIP-6 Packages

DEVICES PER TUBS			
TYPE	UNITS/TUBE	TUBES/BOX	UNITS/BOX
DIP-6	50	40	2000

DIP-6

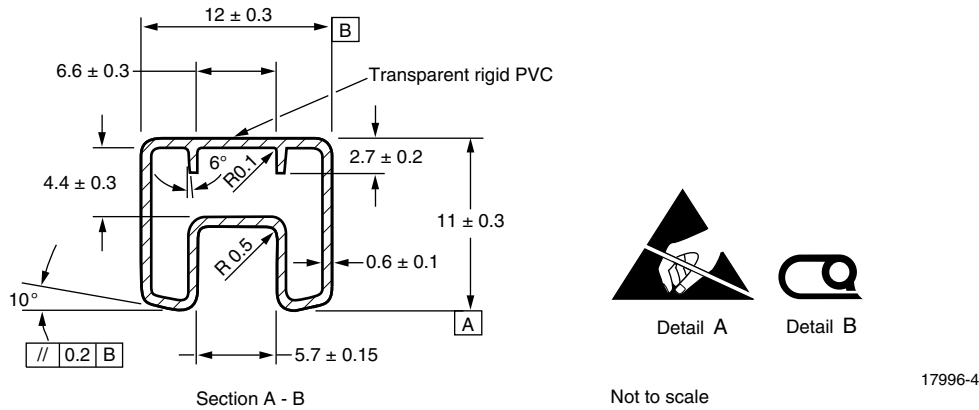


Fig. 10 - Tube Shipping Medium

DIP-6, 400 mil, Option 6

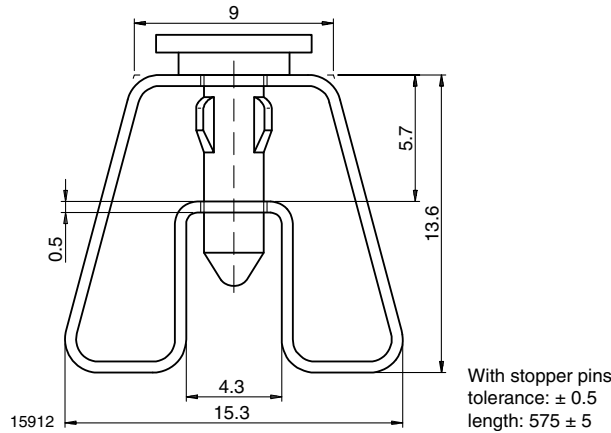


Fig. 11 - Tube Shipping Medium

Tape and Reel

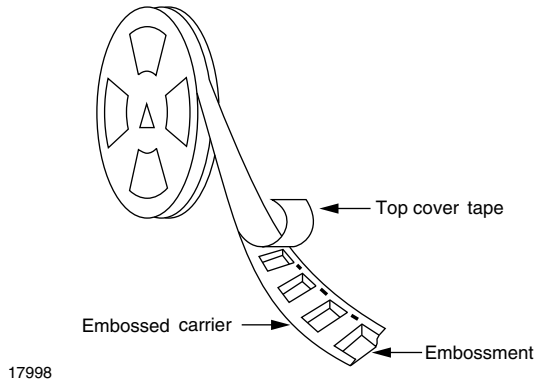


Fig. 12 - Tape and Reel Shipping Medium

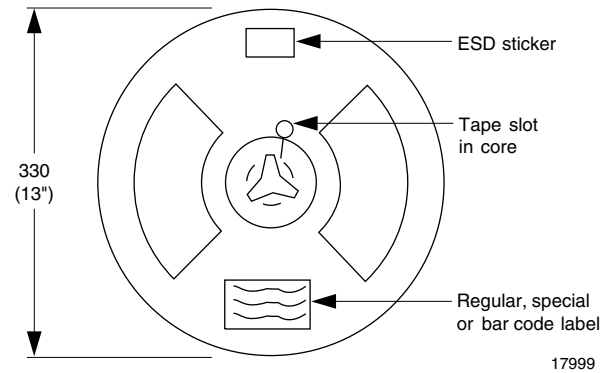


Fig. 13 - Tape and Reel Shipping Medium

SMD-6, Option 7

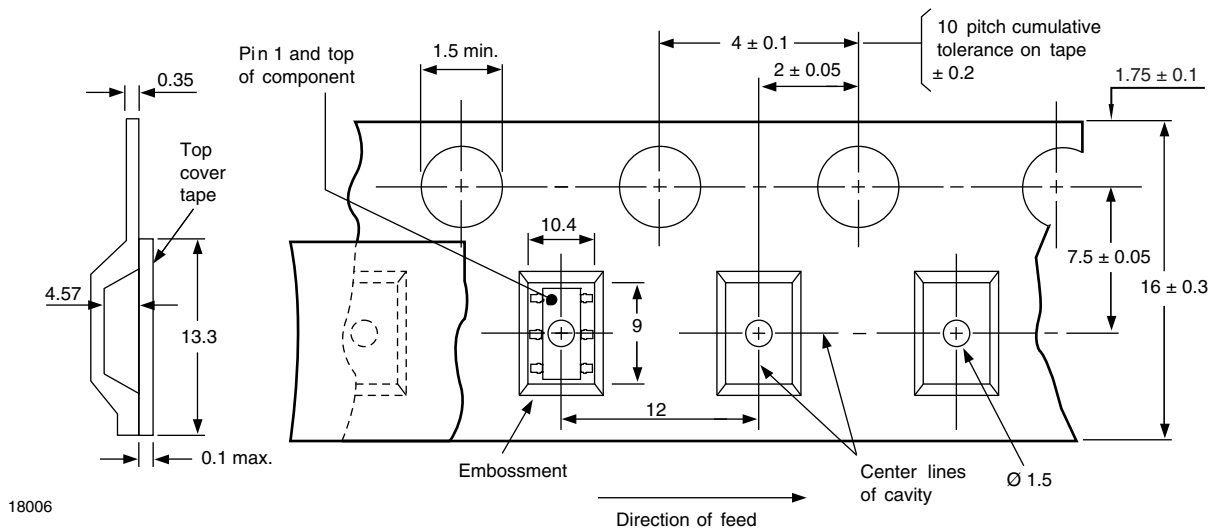


Fig. 14 - Tape and Reel Packing (1000 pieces on Reel)

SMD-6, Option 9

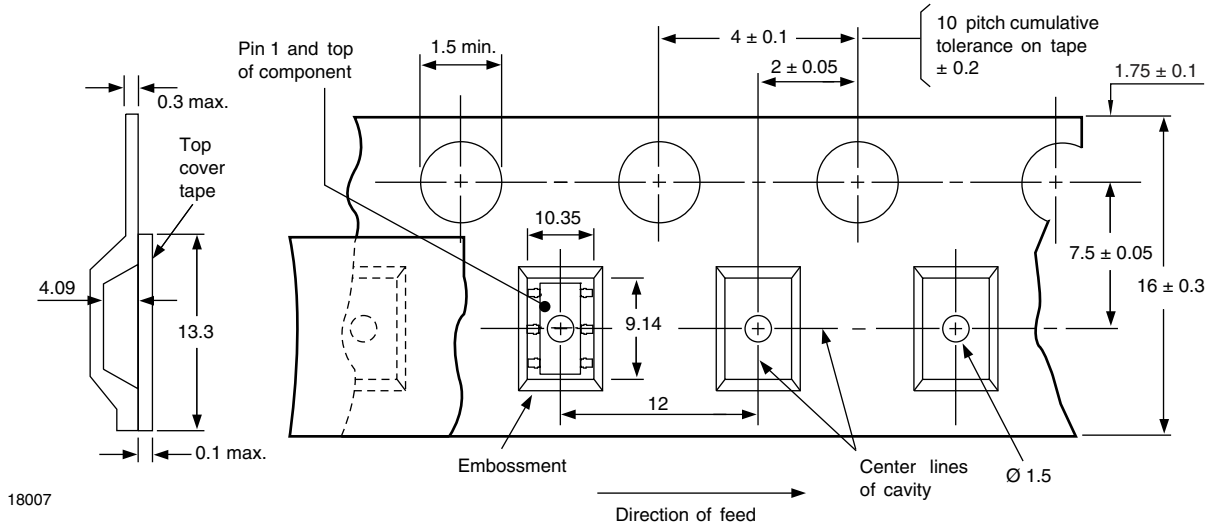


Fig. 15 - Tape and Reel Shipping Medium

SOLDER PROFILES

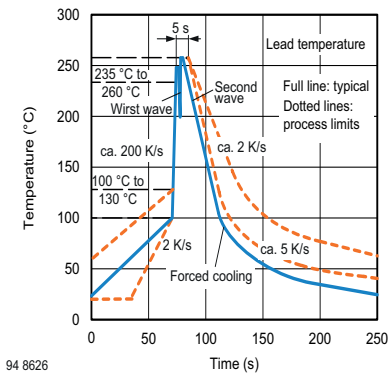


Fig. 16 - Wave Soldering Double Wave Profile According to J-STD-020 for DIP Devices

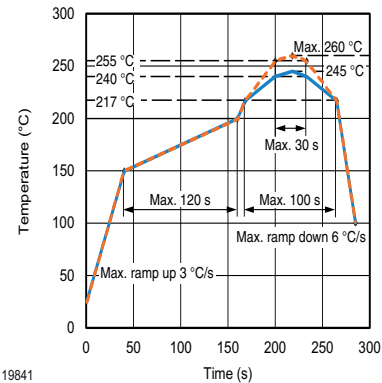


Fig. 17 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020 for SMD Devices

HANDLING AND STORAGE CONDITIONS

ESD level: HBM class 2

Floor life: unlimited

Conditions: $T_{amb} < 30\text{ °C}$, $RH < 85\%$

Moisture sensitivity level 1, according to J-STD-020



Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.